Universal Hexadecimal Counter

Description

The MC10H136 is a high speed synchronous hexadecimal counter. This 10H part is a functional/pinout duplication of the standard MECL 10K[™] family part, with 100% improvement in counting frequency and no increase in power-supply current.

Features

- Counting Frequency, 250 MHz Minimum
- Power Dissipation, 625 mW Typical
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K Compatible
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant



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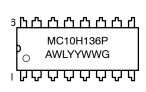
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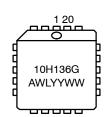




PDIP-16 P SUFFIX CASE 648-08 PLLC-20 FN SUFFIX CASE 775-02

MARKING DIAGRAMS*





A = Assembly Location

WL = Wafer Lot
 YY = Year
 WW = Work Week
 G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
MC10H136FNG	PLCC-28 (Pb-Free)	46 Units/Tube
MC10H136PG	PDIP-16 (Pb-Free)	25 Units/Tube

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}For additional marking information, refer to Application Note <u>AND8002/D</u>.

Table 1. FUNCTION SELECT TABLE

CĪN	S1	S2	Operating Mode
Х	L	L	Preset (Program)
L	L	Н	Increment (Count Up)
Н	L	Н	Hold Count
L	Н	L	Decrement (Count Down)
Н	Н	Ĺ	Hold Count
Х	Н	Н	Hold (Stop Count)

Table 2. SEQUENTIAL TRUTH TABLE*

	INPUTS						OUTPUTS					
S1	S2	D0	D1	D2	DЗ	Carry In	Clock * *	Q0	Q1	Q2	Qз	Carry Out
L	L	L	L	Η	Τ	Х	Н	L	L	Η	Τ	L
L	Н	Х	Х	Х	Х	L	Н	Н	L	Н	Н	Н
L	Н	Х	Х	Х	Х	L	Н	L	Н	Н	Н	Н
L	н	Х	Х	Х	Х	L	Н	Н	Н	Н	Н	L
L	Н	Х	Х	Х	Х	Н	L	Н	Н	Н	Н	Н
L	Н	Х	Х	Х	Х	Н	Н	Н	Н	Н	Н	Н
Н	Н	Х	Х	Х	Х	Х	Н	Н	Н	Н	Н	н
L	L	Τ	Τ	L	L	Х	Н	Н	Н	L	L	L
Н	L	Х	Х	Х	Х	L	Н	L	Н	L	┙	Н
Н	L	Х	Х	Х	Х	L	Н	Н	L	L	L	Н
Н	L	Х	Х	Х	Х	L	Н	L	L	L	L	L
Н	L	Х	Х	Х	Х	L	Н	Н	Τ	Н	Τ	Η

Pin assignment is for Dual-in-Line Package.

Figure 1. Pin Assignment

Table 3. MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
V _{EE}	Power Supply (V _{CC} = 0)	-8.0 to 0	Vdc
VI	Input Voltage (V _{CC} = 0)	0 to V _{EE}	Vdc
l _{out}	Output Current Continuous Surge	50 100	mA
T _A	Operating Temperature Range	0 to +75	°C
T _{stg}	Storage Temperature Range Plastic Ceramic	–55 to +150 –55 to +165	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 4. ELECTRICAL CHARACTERISTICS (V_{EE} = -5.2 V $\pm 5\%$) (Note 1)

		()°	2:	5°		75°	
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
ΙE	Power Supply Current	-	165	-	150	-	165	mA
linH	Input Current High Pins 5, 6, 11, 12, 13 Pin 9 Pin 7 Pin 10	- - - -	430 670 535 380	- - - -	275 420 335 240	- - - -	275 420 335 240	μΑ
I _{inL}	Input Current Low	0.5	-	0.5	-	0.3	-	μΑ
V _{OH}	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
V _{OL}	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
V _{IH}	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
V _{IL}	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

^{1.} Each MECL 10H™ series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained. Outputs are terminated through a 50 Ω resistor to –2.0 V.

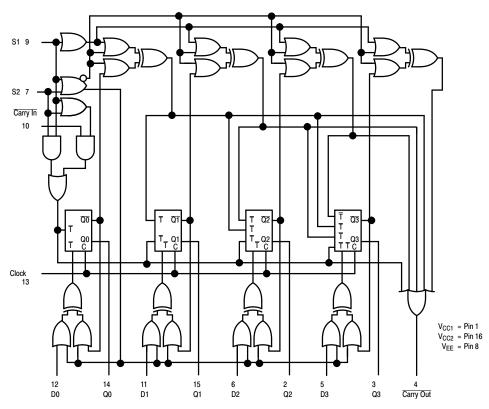
 $[\]neg v_{cc2}$ Q1 Q3 14 Q0 13 CLOCK Cout D3 D0 D2 11 D1 10 CIN S2 9 S1 V_{EE}

^{*} Truth table shows logic states assuming inputs vary in sequence shown from top to bottom.
** A clock H is defined as a clock input transition from a low to a high logic level.

Table 5. AC CHARACTERISTICS

		C) °	2	5°	7	75°	
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
t _{pd}	Propagation Delay Clock to Q Clock to Carry Out Carry in to Carry Out	0.7 1.0 0.7	2.3 4.8 2.5	0.7 1.0 0.7	2.4 4.9 2.6	0.7 1.0 0.7	2.5 5.0 2.7	ns
^t set	Set-up Time Data (D0 to C) Select (S to C) Carry In (C _{in} to C) (C to C _{in})	2.0 3.5 2.0 0	- - - -	2.0 3.5 2.0 0	- - - -	2.0 3.5 2.0 0	- - - -	ns
t _{hold}	Hold Time Data (C to D0) Select (C to S) Carry In (C to C _{in}) (C _{in} to C)	0 -0.5 0 2.2	- - - -	0 -0.5 0 2.2	- - - -	0 -0.5 0 2.2	- - - -	ns
f _{count}	Counting Frequency	250	-	250	-	250	-	MHz
t _r	Rise Time	0.5	2.3	0.5	2.4	0.5	2.5	ns
t _f	Fall Time	0.5	2.3	0.5	2.4	0.5	2.5	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.



NOTE: FLIP-FLOPS WILL TOGGLE WHEN ALL $\overline{\mathsf{T}}$ INPUTS ARE LOW.

Figure 2. Logic Diagram

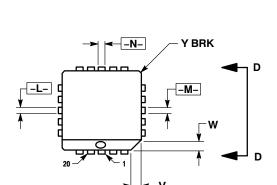
APPLICATION INFORMATION

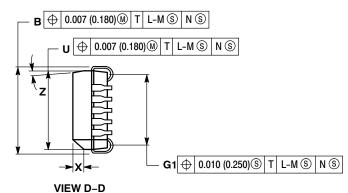
The MC10H136 is a high speed synchronous counter that operates at 250 MHz. Counter operating modes include count up, count down, pre-set and hold count. This device allows the designer to use one basic counter for many applications.

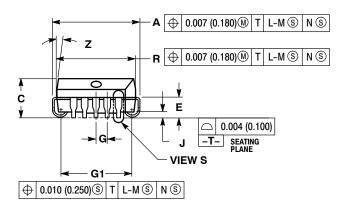
The S1, S2, control lines determine the operating modes of the counter. In the pre-set mode, a clock pulse is necessary to load the counter with the information present on the data inputs (D0, D1, D2, and D3). Carry out goes low on the terminal count or when the counter is being pre-set.

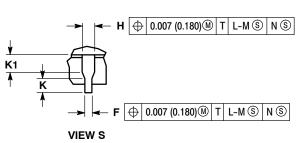
PACKAGE DIMENSIONS

20 LEAD PLLC CASE 775-02 **ISSUE F**









- 1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M,
- 2. DIMENSIONS IN INCHES.
 3. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD

 OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

- PARTING LINE.

 4. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

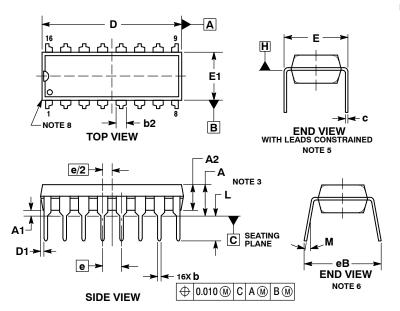
 5. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

 6. DIMENSIONS IN THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
 7. DIMENSION H DOES NOT INCLUDE DAMBAR
- DIMENSION OF INTRUSION. THE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.021	0.33	0.53
G	0.050	BSC	1.27	BSC
н	0.026	0.032	0.66	0.81
J	0.020		0.51	-
K	0.025		0.64	-
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Х	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10 °	2°	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

PACKAGE DIMENSIONS

PDIP-16 CASE 648-08 **ISSUE V**



NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: INCHES. DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
- DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS ARE NOT TO EXCEED 0.10 INCH
- DIMENSION E IS MEASURED AT A POINT 0.015 BELOW DATUM PLANE H WITH THE LEADS CONSTRAINED PERPENDICULAR TO DATUM C
- DIMENSION eB IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
 DATUM PLANE H IS COINCIDENT WITH THE BOTTOM OF THE
- LEADS, WHERE THE LEADS EXIT THE BODY.
 PACKAGE CONTOUR IS OPTIONAL (ROUNDED OR SQUARE
- CORNERS)

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α		0.210		5.33	
A1	0.015		0.38		
A2	0.115	0.195	2.92	4.95	
b	0.014	0.022	0.35	0.56	
b2	0.060	TYP	1.52 TYP		
С	0.008	0.014	0.20	0.36	
D	0.735	0.775	18.67	19.69	
D1	0.005		0.13	-	
E	0.300	0.325	7.62	8.26	
E1	0.240	0.280	6.10	7.11	
е	0.100 BSC		2.54 BSC		
eB		0.430		10.92	
L	0.115	0.150	2.92	3.81	
M		10°		10°	

STYLE 1	:	STYLE 2	:
PIN 1.	CATHODE	PIN 1.	COMMON DRAIN
2.	CATHODE	2.	COMMON DRAIN
3.	CATHODE	3.	COMMON DRAIN
4.	CATHODE	4.	COMMON DRAIN
5.	CATHODE	5.	COMMON DRAIN
6.	CATHODE	6.	COMMON DRAIN
7.	CATHODE	7.	COMMON DRAIN
8.	CATHODE	8.	COMMON DRAIN
9.	ANODE	9.	GATE
10.	ANODE	10.	SOURCE
11.	ANODE	11.	GATE
12.	ANODE	12.	SOURCE
13.	ANODE	13.	GATE
14.	ANODE	14.	SOURCE
15.	ANODE	15.	GATE
16.	ANODE	16.	SOURCE

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